Overview

HP ZBook Fury 15.6 Inch G8 Mobile Workstation PC



- 1. Ambient Light Sensor
- 2. Internal Microphones (optional)
- 3. Camera LEDs (optional)
- 4. HD Camera (optional)
- 5. IR Camera (optional)
- 6. Camera Cover (optional)
- 7. Speakers with Discrete Amplifier
- 8. Function Keys (changes with configured options)
- 9. Power button
- 10. HP Programmable Key
- 11. Numeric Keypad
- 12. Pointstick

¹SuperSpeed USB 20Gbps is not available with Thunderbolt[™] 4.

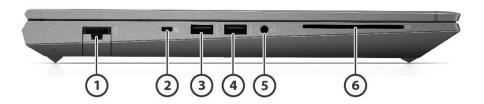
Right

- 13. Fingerprint Sensor (optional)
- 14. Touchpad
- 15. 3-button Touchpad
- 16. Indicator LEDs: Power light, Wireless light, Storage usage light
- 17. Power connector
- 18. USB Type-C[®] with Thunderbolt[™] 4¹
- 19. USB Type-C[®] with Thunderbolt[™] 4¹
- 20. Mini DisplayPort™ 1.4 with Discrete Graphics ²
- 21. HDMI port
- 22. SD Card Reader



² Mini DisplayPort™ 1.4 with discrete, 1.2 with UMA.

Overview



Left

- 1. RJ-45
- 2. Nano security lock slot
- 3. USB 3.1 Gen 1 Charging Port

- 4. USB 3.1 Gen 1
- 5. Audio Combo Jack
- 6. Smart Card Reader



Overview

At A Glance

- Work anywhere without compromising on performance or security with Windows 10 Pro ¹, powered by HP's collaboration and connectivity technology.
- Accelerate your workflow. Power through projects with up to 128 GB RAM ² for fast rendering, editing and visual effects performance.
- Take multitasking to the next level with the Intel® Core™ i9 processor ³ designed to handle complex, multithreaded apps like Adobe® Premier Pro, and with fast clock speeds you can boost your speed on single threaded apps like Autodesk 3ds Max ⁴
- Run demanding professional apps with the newest generation Intel® Xeon® processors 5 for powerful performance and productivity.
- Experience high-end visualization and seamlessly render your biggest projects with the next generation NVIDIA® Ampere architecture with NVIDIA® T-Series and RTX A graphics¹⁹; Certified and supported for the apps you use every day.
- Strenuously tested to meet software certification and deliver superb performance with leading software providers, including Autodesk and Adobe® 6.
- Blitz through multiple tasks and ditch external drives with up to 8 TB ⁷, local PCIe NVMe storage up to 21x faster than standard HDD and 6x faster than SATA SSD ⁹.
- Instantly protect against visual hacking with HP Sure View ¹⁰, and defend against firmware and malware attacks with HP Sure Start ¹¹ and HP Sure Sense ¹², and have peace of mind with multi-factor authentication- including an infrared camera and fingerprint scanner ¹³.
- Enhanced transfer and upload speeds via dual Thunderbolt™ 4 ports. Get wide-ranging connectivity options to ensure maximum device interaction: USB 3.0, HDMI, mDP, SD card, Smart Card Reader and more.
- Designed for ultimate durability, this ZBook undergoes brutal MIL-STD 810H ¹⁴ tests to help ensure this PC keeps rolling through your workday.
- Plug in to greater connectivity at your desktop with the HP Thunderbolt Dock for lightning-fast Thunderbolt™ 4 ¹⁵ transfers and the flexibility to run more than up to 2 external 4k ^{16,17}.
- Improve connectivity while on Wi-Fi® with HP Extended Range Wireless LAN that allows greater distance from transmission point and fast data throughput at shorter ranges ¹⁸.

NOTE: See important legal disclosures for all listed specs in their respective features sections.



Features

OPERATING SYSTEM

Preinstalled OS Windows® 11 Pro1 - HP recommends Windows® 11 Pro1

Windows® 11 Home¹

Windows® 11 Home Single Language¹

Windows® 11 Pro (Windows® 11 Enterprise available with a Volume Licensing Agreement)1

Windows® 10 Pro (available through downgrade rights from Windows® 11 Pro)1,3

Windows® 11 Pro for Workstations1

Windows® 10 Pro for Workstations (available through downgrade rights from Windows® 11 Pro for

Workstations)^{1,3} Windows[®] 10 Pro^{1,2} Windows[®] 10 Home^{1,2}

Windows® 10 Home Single Language^{1,2}

Windows® 10 Pro (Windows® 10 Enterprise available with a Volume Licensing Agreement)^{1,2}

Windows® 10 Pro for Workstations1

FreeDOS 3.0

Ubuntu Linux 20.044

Web support OS Red Hat® Enterprise Linux® 84

Windows® 10 Enterprise 641

Supported Version HP tested Windows 10, version 1909 on this platform. For testing information on newer versions of

Windows 10, please see https://support.hp.com/document/c05195282

¹ Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

² This PC comes with Windows 10 and a free Windows 11 upgrade. The Windows 11 upgrade will be delivered late 2021 into 2022. Timing varies by device. Certain features require specific hardware. See aka.ms/windows11-spec

³ This system is preinstalled with Windows 10 Pro software and also comes with a license for Windows 11 Pro software and provision for recovery software. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version. You must back up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data.

⁴ For detailed Linux® OS/hardware support information, see: http/www.hp.com/linux hardware matrix

PROCESSOR

11th Generation Intel® Xeon® W-11955M vPro® with Intel® UHD Graphics (2.6 GHz base frequency, up to 5.0 GHz with Intel® Turbo Boost Technology, 24 MB cache, 8 cores)^{1,2,3,4,5}

11th Generation Intel® Core™ i9-11950H vPro® with Intel® UHD Graphics (2.6 GHz base frequency, up to 5.0 GHz with Intel® Turbo Boost Technology, 24 MB cache, 8 cores) 1,2,3,4,5

11th Generation Intel® Core™ i9-11900H with Intel® UHD Graphics (2.5 GHz base frequency, up to 4.9 GHz with Intel® Turbo Boost Technology, 24 MB L3 cache, 8 cores) ^{1,2,3,4,5}

11th Generation Intel® Core™ i7-11850H vPro® with Intel® UHD Graphics (2.5 GHz base frequency, up to 4.8 GHz with Intel® Turbo Boost Technology, 24 MB L3 cache, 8 cores) 1,2,3,4,5

11th Generation Intel® Core™ i7 11800H with Intel® UHD Graphics (2.3 GHz base frequency, up to 4.6 GHz with Intel® Turbo Boost Technology, 24 MB L3 cache, 8 cores)^{1,2,3,4,5}

11th Generation Intel® Core™ i5-11500H vPro® with Intel® UHD Graphics (2.9 GHz base frequency, up to 4.6 GHz with Intel® Turbo Boost Technology, 12 MB L3 cache, 6 cores)^{1,2,3,4.5}



Features

- ¹ Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.
- ² Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.
 ³ Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. Energy Efficient Turbo is a power management feature that can lower the maximum core ratio (frequency), if the CPU thinks it can achieve about the same performance as with the maximum turbo frequency. Energy Efficient Turbo feature is disabled in Comet Lake H in order to prioritize performance in DC mode. It can be changed in F10 BIOS settings. See www.intel.com/technology/turboboost for more information. In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and
- forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.

 ⁵ For full Intel® vPro® functionality, Windows 10 Pro 64 bit, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and/or WLAN card and TPM 2.0 are required. Some functionality requires additional 3rd party software in order to run. See http://intel.com/vpro



Features

CHIPSET

Mobile Intel® TigerLake PCH-H, WM 590

INTEL® CORE™ I5 WITH VPRO/CORE I7 WITH VPRO/XEON® WITH VPRO TECHNOLOGY CAPABLE

Intel® Core™ i5 with vPro™, Core™ i7 with vPro™, Core™ i9 with vPro™ and Xeon® with vPro™ technology is a selectable feature that is available on units configured with select processors, a qualified Intel® WLAN module and a preinstalled Windows® operating system. It provides advances in remote manageability, security, energy efficient performance, and wireless connectivity. Intel® Active Management Technology (iAMT) offers built-in manageability and proactive security for networked mobile workstations, even when they are powered off* or when the operating system is inoperable. It can help identify threats before they reach the network, isolate infected systems, and update regardless of their power state. ^{1,2}

GRAPHICS

Integrated

Intel® UHD Graphics 1,2,3,4,5

Discrete

NVIDIA Graphic options:

NVIDIA RTX™ A5000 (16 GB GDDR6 dedicated)^{1,2,3,4,5,7}

NVIDIA RTX™ A4000 (8 GB GDDR6 dedicated)^{1,2,3,4,5,7}

NVIDIA RTX™ A3000 (6 GB GDDR6 dedicated)^{1,2,3,4,5,7}

NVIDIA RTX™ A2000 (4 GB GDDR6 dedicated)1,2,3,4,5

NVIDIA® T1200 (4 GB GDDR6 dedicated) 1,2,3,4,5

AMD Graphic options:

AMD Radeon Pro W6600M (8 GB GDDR6 dedicated) 1,2,3,4,5,7

Multi Display Support



¹ Requires a Windows operating system, network hardware and software, connection with a power source, and a direct (non-VPN) corporate network connection which is either cable or wireless LAN.

² For full Intel® vPro® functionality, Windows 10 Pro 64 bit, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and/or WLAN card and TPM 2.0 are required. Some functionality requires additional 3rd party software in order to run. See http://intel.com/vpro

¹ UHD content required to view UHD images.

² Support HD decode, DX11, DX12, HDMI 2.0b, HDCP 2.3 via DP up to 4K @ 60Hz and via HDMI up to 4K @ 60Hz (NVIDIA RTX™ A5000, RTX A4000, RTX A3000, RTX A2000, AMD Radeon Pro W6600M support HDMI 2.1 with FRL)

³ HDMI cable Sold Separately

⁴ Shared video memory (UMA) uses part of the total system memory for video performance. System memory dedicated to video performance is not available for other use by other programs.

⁵ miniDP cable sold separately.

⁶ GPU configurations may be limited to specific panel options

⁷ The HP custom vapor chamber (Z VaporForce) is only available on configurations with NVIDIA® RTX™ A3000 graphics and greater or AMD Radeon graphics

Features

Without HP Thunderbolt™ Dock G2

UMA Graphics: Unit supports up to 3 independent displays. Any combination of displays outputs may be used except one of Thunderbolt™ 4 and HDMI.

Hybrid Graphics (NVIDIA): Unit supports up to 4 independent displays. Any combination of displays outputs may be used except when using one USBC and HDMI are exclusive

Hybrid Graphics (AMD): Unit supports up to 4 independent displays. Any combination of displays outputs may be used except when using one USBC and HDMI are exclusive

NOTE: If Thunderbolt™ only port on the dock is connected, then the three external displays will not function.

With HP Thunderbolt™ Dock G2

UMA Graphics: Unit supports up to 3 independent displays. Any combination of displays outputs may be used except one of Thunderbolt™ 4 and HDMI.

Hybrid Graphics (NVIDIA): Unit supports up to 4 independent displays. Any combination of displays outputs may be used except when using one USBC and HDMI are exclusive

Hybrid Graphics (AMD): Unit supports up to 6 independent displays. Any combination of displays outputs may be used except when using one USBC and HDMI are exclusive

NOTE: Resolutions are dependent upon monitor capability and resolution and color depth settings.

DISPLAY

Non-touch

- 15.6" diagonal FHD (1920 x 1080) IPS eDP1.2 anti-glare WLED-backlit and ambient light sensor 250 nits 45% NTSC^{1,2}
- 15.6" diagonal FHD (1920 x 1080) IPS eDP1.3 + PSR anti-glare WLED-backlit and ambient light sensor 400 nits 72% NTSC
- 15.6" diagonal FHD (1920 x 1080) IPS eDP1.3 + PSR anti-glare WLED-backlit and ambient light sensor 1000 nits 72% NTSC Next Gen HP SureView Reflect 1,2,5,7
- Next Gen HP Dream Color display 15.6" diagonal UHD (3840 x 2160) IPS 120Hz eDP1.4 + PSR2 anti-glare BV LED-backlit and ambient light sensor 600 nits 100% DCI-P3^{1,2,3}

Touch

 15.6" diagonal UHD (3840 x 2160) IPS eDP1.4 + PSR2 WLED-backlit touch screen with Corning® Gorilla® Glass 5 and ambient light sensor 600 nits 100% DCI-P3 1,2,3,7

HP Virtual Reality⁶ Headset (sold separately)

- HP Reverb
- HP Reverb G2



¹ UHD content required to view UHD images.

² Resolutions are dependent upon monitor capability, and resolution and color depth settings.

³ Display options may be limited to specific GPU Configurations.

⁵ HP Sure View Reflect is optional and must be configured at purchase.

⁶ Virtual Reality content is required to view Virtual Reality images

⁷Actual brightness will be lower with Sure View or touchscreen.

Features

STORAGE AND DRIVES*

Max Storage

8TB through four M.2 NVMe drives 6TB through two M.2 NVMe drives and one 2.5" SATA drive

(up to 1) HDD Storage (SATA 3.2)4

500 GB 7200 rpm SATA FIPS 140-2 SED HDD 500 GB 7200 rpm SATA HDD 1 TB 7200 rpm SATA HDD 2 TB 5400 rpm SATA HDD

(up to 4) M.2 Storage (NVMe™ PCIe SSD)

256 GB PCIe (NVMe™) TLC Solid State Drive 256 GB PCIe (NVMe™) TLC Self Encrypting (SED) Solid State Drive 512 GB PCIe (NVMe™) TLC Solid State Drive 512 GB PCIe (NVMe™) TLC Self Encrypting (SED) Solid State Drive 1 TB PCIe (NVMe™) TLC Solid State Drive³ 1 TB PCIe (NVMe™) TLC Self Encrypting (SED) Solid State Drive 2 TB PCIe (NVMe™) TLC Solid State Drive³ 2 TB PCIe (NVMe™) TLC Self Encrypting (SED) Solid State Drive

256 GB PCIe Gen4 (NVMe™) TLC Solid State Drive^{5,**}
256 GB PCIe Gen4 (NVMe™) TLC Self Encrypting (SED) OPAL2 Solid State Drive^{5,**}
512 GB PCIe Gen4 (NVMe™) TLC Solid State Drive^{5,**}
512 GB PCIe Gen4 (NVMe™) TLC Self Encrypting (SED) OPAL2 Solid State Drive^{5,**}
1 TB PCIe Gen4 (NVMe™) TLC Solid State Drive^{5,**}
2 TB PCIe Gen4 (NVMe™) TLC Solid State Drive^{5,**}

DRIVE CONTROLLERS

M.2 Storage Bay (PCIe NVMe)
RAID:

PCIe Gen 3 x 4 lanes NVMe Solid State Drive

RAID 0 and RAID 1 support¹

- 1 Support only available with 1TB + 1TB M.2 storage or 2TB + 2TB M.2 storage combinations
- ² Not available if slots if storage slots 3 or 4 are selected

MEMORY

Maximum Memory^{2,3,5}

128 GB DDR4-3200 non-ECC SDRAM DIMM1, DIMM3, DIMM2, DIMM4 64 GB DDR4-3200 ECC SDRAM

4 DDR4 SODIMMS4

Supports Dual Channel Memory¹



¹Storage slot 1-4 can support NVMe protocol

²Storage slot 1, 3 and 4 can support SATA protocol

³Only storage slots 1-3 can support RAID

⁴System is preset to Modern Standby Disconnected with factory preinstall image

⁵PCIe Gen4 drives will only work at PCIe Gen3 speed.

^{*} For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35GB of disk is reserved for system recovery software.

^{**} Available late September 2021.

Features

Slots are customer accessible / upgradeable

- ¹Maximized dual-channel performance requires SODIMMs of the same size and speed in both memory channels.
- ² Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.
- ³Transfer rates up to 3200 MT/s for nECC and ECC memory combinations when memory suppliers are consistent. If suppliers are not consistent, speeds may drop to 2933 MT/s for nECC and 2933 MT/s for ECC memory combinations. A custom configuration including part number AY104AV can be used to lock in a consistent vendor.
- ⁴Intel[®] allows architectures designed with four DIMM slots to run at 3200 MT/s
- ⁵Maximum memory capacities assume Windows 64-bit operating systems. With Windows 32-bit operating systems, memory above 3 GB may not all be available due to system resource requirements.



Features

NETWORKING/COMMUNICATIONS

ΙΔΝ

Intel® I219-LM GbE, vPro™
Intel® I219-V GbE, non-vPro™

¹GbE - The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

WLAN

Intel® Wi-Fi 6 AX201 (2x2) and Bluetooth® 5.2 combo, vPro^{™ 1}
Intel® Wi-Fi 6 AX201 (2x2) and Bluetooth® 5.2 combo, non-vPro^{™ 1,2}

¹Wireless cards are optional or add-on features and requires separately purchased wireless access point and internet service. Availability of public wireless access points limited. Only available in countries where 802.11ax is supported.

² Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax WLAN devices. Only available in countries where 802.11ax is supported.

WWAN1

Intel® XMM™ 7360 LTE Advanced CAT 93

Nano SIM card slot^{2,3}

A removable SIM is an orderable option for selected 4G LTE notebooks. The removable physical eSIM is placed on the SIM tray on the notebook like a standard SIM card. The removable eSIM is programmable and is not limited to a single carrier. You must add eSIM profile to connect to the internet using cellular data.

¹ WWAN use requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, and in all regions.

² All units have an internal SIM card slot but 'For WWAN' base units ship with antennas.

Optional Near Field Communication (NFC) module

AUDIO/MULTIMEDIA

Audio

Audio by Bang & Olufsen, dual stereo speakers, HP World Facing Microphone dual array digital microphone¹, functions keys for volume up and down, combo microphone/headphone jack, HD audio

¹Dual-microphone array when equipped with optional webcam and optional world facing microphone.

Camera^{1, 2, 3}

720p HD webcam with IR 720p HD webcam

¹ FHD and HD content required to view HD images respectively.



³ Works with Windows 10 only.

Features

² Windows Hello face authentication utilizes a camera specially configured for near infrared (IR) imaging to authenticate and unlock Windows devices as well as unlock your Microsoft Passport.

³Camera-configured options come with a Privacy Shutter



Features

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

HP Premium Quiet Keyboard, full-size, spill-resistant, backlit, a Programmable Key, with sperate numeric keypad, HP DuraKey, touchpad with glass surface, multi-touch gestures and taps enabled

Pointing Devices

Dual pointstick; Touchpad with multi-touch gestures enabled, taps enabled as default; Microsoft Precision Touchpad Default Gestures Support

SOFTWARE AND SECURITY

Workstation ISV Certifications

See the latest list of certifications at: http://www.hp.com/go/isv

HP ZCENTRAL REMOTE BOOST SOFTWARE

The remote desktop solution for serious workstation users and their most demanding applications. Download at: http://www.hp.com/go/RGS

HP Performance Advisor

HP Performance Advisor enables optimal configuration of HP Mobile Workstations delivering stability and best performance. HP Performance Advisor will guide your system setup allowing a "custom" configuration that best matches the workstation to user requirements. Download at: http://www.hp.com/go/performanceadvisor

Software

Adobe Creative Cloud Bundle

Bing search for IE11

Buv Office

Data Science Stack

HP Admin

HP Connection Optimizer^{20,9}

HP Cloud Recovery²¹

HP Easy Clean

HP PC Hardware Diagnostics

HP Privacy Settings

HP Hotkey Support

HP JumpStart

HP Noise Cancellation Software

HP Performance Advisor8

HP QuickDrop²²

HP Recovery Manager

HP Remote Graphics Software

HP Smart Support¹⁹

HP Support Assistant¹

HP ZCentral Remote Boost 2020 Software for Z workstation^{23,2}

Native Miracast support

Tile Application

Security Management

Absolute persistence module^{32,6}

HP BIOSphere Gen6^{30,5}

HP Client Security Suite Gen7¹⁶

HP Device Access Manager

HP FingerPrint Sensor

HP Manageability Integration Kit^{24,11}



Features

HP Power On Authentication

HP Secure Erase³¹

HP Security Manager

HP Secure Platform

HP Sure Click²⁶

HP Sure Recover Gen4^{28,13}

HP Sure Run²⁷

HP Sure Sense^{25,17}

HP Sure Start Gen6^{29,14}

HP SureView Reflect:

HP Tamper Lock

Master Boot Record security:

Microsoft Defender¹⁰

Pre-boot authentication

Nano security lock slot12

Smartcard Reader - Alcor AU9560 (FIPS 201 Compliant)

Trusted Platform Module TPM 2.0 Embedded Security Chip with Windows 10 (Common Criteria EAL4+ Certified)(FIPS 140-2

Level 2 Certified)³³ Windows Secured Core

BIOS Version

ISO/IEC 19678: 2015 (formerly NIST 800-147) compliant

UEFI version: 2.7

TPM

Model: Infineon SLB9670

Version: 7.85 Revision: TPM 2.0

FIPS 140-2 Compliant: Yes

Smartcard Reader

Model Number: Alcor AU9560 FIPS 201 Compliant: Yes

For more information on HP Client Security Software Suite, refer to http://www.hp.com/go/clientsecurity.

¹² Nano Security lock slot is Lock sold separately.



¹ HP Support Assistant - Requires Windows and Internet Access.

² HP ZCentral Remote Boost Sender does not come preinstalled on Z Workstations but can be downloaded and run on all Z desktop and laptops without license purchase. With non-Z sender devices, purchase of perpetual individual license or perpetual floating license per simultaneously executing versions and purchase of ZCentral Remote Boost Software Support is required. ZCentral Remote Boost Sender for non-Z Hardware requires a license and Windows 10, RHEL/CentOS (7 or 8), or UBUNTU 18.04 or 20.04 LTS operating systems. macOS (10.14 or newer) operating system and ThinPro 7.2 are only supported on the receiver side. Requires network access. The software is available for download at hp.com/ZCentralRemoteBoost.

⁵ HP BIOSphere Gen6 is available on select HP Pro, Elite and ZBook PCs. See product specifications for details. Features may vary depending on the platform and configurations. ⁶ Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: http://www.absolute.com/company/legal/agreements/computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.

⁸ HP Performance Advisor Software - HP Performance Advisor is ready and waiting to help you get the most out of your HP Workstation from day one—and every day after. Learn more or download at: https://www8.hp.com/us/en/workstations/performance-advisor.html

⁹ HP Connection Optimizer requires Windows 10.

¹⁰ Microsoft Defender Opt in and internet connection required for updates.

¹¹ HP Manageability Integration Kit can be downloaded from http://www.hp.com/go/clientmanagement.

Features

- ¹³ HP Sure Recover Gen3: See product specifications for availability. Requires an open, wired network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. HP Sure Recover (Gen1) does not support platforms with Intel® Optane™.
- ¹⁴ HP Sure Start Gen6 is available on select HP PCs with Intel processors. See product specifications for availability.
- ¹⁵ For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.
- ¹⁶ HP Client Security Manager Gen5 requires Windows and is available on select HP Pro, Elite and ZBook PCs. See product specifications for details.
- ¹⁷ HP Sure Sense requires Windows 10. See product specifications for availability.
- 18 Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited.
- ¹⁹ HP Smart Support is available to commercial customers through your HP Service Representative and HP Factory Configuration Services; or it can be downloaded at: http://www.hp.com/smart-support. HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights.
- ²⁰ HP Connection Optimizer requires Windows 10.
- ²¹ HP Cloud Recovery is available for Z by HP, HP Elite and Pro desktops and laptops PCs with Intel® or AMD processors and requires an open, wired network connection. Note: You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Detail please refer to: https://support.hp.com/us-en/document/c05115630
- ²² HP QuickDrop requires Internet access and Windows 10 PC preinstalled with HP QuickDrop app and either an Android device (phone or tablet) running Android 7 or higher with the Android HP QuickDrop app, and /or an iOS device (phone or tablet) running iOS 12 or higher with the iOS HP QuickDrop app.
- ²³ HP ZCentral Remote Boost Sender does not come preinstalled on Z Workstations but can be downloaded and run on all Z desktop and laptops without license purchase. With non-Z sender devices, purchase of perpetual individual license or perpetual floating license per simultaneously executing versions and purchase of ZCentral Remote Boost Software Support is required. ZCentral Remote Boost Sender for non-Z Hardware requires a license and Windows 10, RHEL/CentOS (7 or 8), or UBUNTU 18.04 or 20.04 LTS operating systems. macOS (10.14 or newer) operating system and ThinPro 7 are only supported on the receiver side. Requires network access. The software is available for download at hp.com/ZCentralRemoteBoost.
- ²⁴HP Manageability Integration Kit can be downloaded from http://www.hp.com/go/clientmanagement.
- ²⁵ HP Sure Sense is available on select HP PCs and is not available with Windows10 Home.
- ²⁶ HP Sure Click requires Windows 10. See https://bit.ly/2PrLT6A_SureClick for complete details.
- ²⁷ HP Sure Run is available on select HP PCs and requires Windows 10.
- ²⁸ HP Sure Recover Gen4 is available on select HP PCs and requires Windows 10 and an open network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. Network based recovery using Wi-Fi is only available on PCs with Intel Wi-Fi Module.
- ²⁹ HP Sure Start Gen6 is available on select HP PCs.
- ³⁰ HP BIOSphere Gen6 features may vary depending on the platform and configuration.
- ³¹ For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.
- ³² Absolute firmware module is shipped turned off and can only be activated with the purchase a license subscription and full activation of the software agent. License subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. Certain conditions apply. For full details visit:
- https://www.absolute.com/about/legal/agreements/absolute/.
- ³³ TPM 2.0 is limited on HP ThinPro/HP Smart Zero, and functionality is dependent upon use of a customer-enabled application that can locate the TPM chip.



Features

POWER

Power Supply

120 W Slim Smart external AC power adapter 150 W Slim Smart external AC power adapter 200 W UltraSlim Smart external AC power adapter

Primary Battery

HP Long Life 8-cell, 94 Wh Li-ion polymer^{2,4} **Note:** batteries are customer replaceable.

Battery life1

MM18: Up to 10 hours and 18 minutes

120 W power adapter is configurable with Intel UMA graphics 150 W power adapter is configurable with NVIDIA® T1200 and RTX A2000 configurations 200 W power adapter is configurable with NVIDIA RTX A3000³ or higher and AMD configurations

Power to System

Up to 100 W via USB-C® (up to 75 W on non HP machines) Separate AC power needed for HP ZBooks that require more than 100 W power delivered via USB-C® alt mode.

¹Battery life will vary depending on the product model, configuration, loaded applications, features, use, wireless functionality and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See MobileMark18 battery benchmark https://bapco.com/products/mobilemark-2018/ for additional details.

²Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year limited warranty as the platform. Refer to http://www.hp.com/support/batterywarranty/ for additional battery information.

³The HP custom vapor chamber (Z VaporForce) is only available on configurations with NVIDIA® RTX™ A3000 graphics and greater or AMD Radeon graphics

⁴Actual battery Watt-hours (Wh) will vary from design capacity. Battery capacity will naturally decrease with shelf life, time, usage, environment, temperature, system configuration, loaded apps, features, power management settings and other factors.

ENVIRONMENTAL

ENERGY STAR® certified and EPEAT® registered where applicable.¹
Low halogen²

¹ Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit www.epeat.net for more information.

² External power supplies, power cords, cables and peripherals are not low halogen. Service parts obtained after purchase may not be low halogen.



Features

WEIGHTS & DIMENSIONS

Dimensions (w x d x h) 36.1 x 24.25 x 2.595 cm 14.21 x 9.55 x 1.0222 in

Max. hinge open angle on: 180°

Weights

Starting at 2.35kg (5.18 lb)

Weight varies by configuration and components.

A deck: Anodized Aluminum + plastic antenna cover + magnesium inner structure

B deck: ; Plastic bezel + Touch has Corning® Gorilla ® Glass 5 (option)

C deck: Anodized Aluminum + magnesium inner structure

D deck: Magnesium Die Cast E door: Magnesium Die Cast

Metal Alloy Hinges

Note:

A = Top

B = Panel Area

C = Keyboard/Touchpad surface

D = Bottom

PORTS/SLOTS

Left side⁶

1 RJ-45

1 SuperSpeed USB Type-A 5Gbps signaling rate (charging) [USB 3.1 Gen 1 Type A charging]

1 SuperSpeed USB Type-A 5Gbps signaling rate [USB 3.1 Gen 1 Type A]

1 headphone/microphone combo

1 smart card reader

Right side⁶

1 power connector

2 USB Type-C® (Thunderbolt™ 48, pass through support DisplayPort™ 1.42, USB 4, with BC 1.2)

1 Mini DisplayPort™ 1.4 with Discrete Graphics²

1 HDMI 2.0b or HDMI 2.1 (depends on graphics selection)^{1,3,4,5,7}

1 SD 7.0 Media Card Reader9

- ¹ HDMI port-cable not included.
- ² Mini DisplayPort™ 1.4 with discrete, 1.2 with UMA.
- ³ HDMI 2.0b with NVIDIA T1200 and UMA (NVIDIA RTX™ A5000, RTX A4000, RTX A3000, RTX A2000, AMD Radeon Pro W6600M support HDMI 2.1 with FRL)
- ⁴ When both USB Type-C® are in use, HDMI cannot be detected
- ⁵ When one USB Type-C[®] is in use, HDMI can be detected if USB Type-C[®] in use is assigned to different channel
- ⁶ When product is under heavy power loading, performance may be reduced to prevent battery drain. Disconnecting USB devices will restore system performance
- ⁷HDMI 2.1 not supported with T1200/UMA GPU
- ⁸ SuperSpeed USB 20Gbps is not available with Thunderbolt[™] 4.
- 9SD4.0 cards will run at SD3 speed for any SD 7.0 host. This is the SD 7.0 standard.

SERVICE AND SUPPORT



Features

HP Services offers 3-year and 1-year limited warranties and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year limited warranty as the platform. Refer to http://www.hp.com/support/batterywarranty/ for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc.

¹Sold separately or as an optional feature. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product. Consult your local HP Customer Support Center for details.

CERTIFICATION AND COMPLIANCE

Energy Efficiency Compliance ENERGY STAR® certified Energy Efficiency Compliance EPEAT® GOLD



Technical Specifications – System Unit

SYSTEM UNIT

Stand-Alone Power Requirements (AC Power)

Nominal Operating

Voltage

19.5V

Average Operating Power(idle)

System in idle mode + max panel brightness

Adapter Safety test

condition

Discrete Graphics 80W Max Operating Power <200W

Temperature Operating 32° to 95° F (0° to 35° C) (Not Writing Optical)

Non-operating

-4° to 140° F (-20° to 60° C) (writing optical)

Relative Humidity

10% to 90%, non-condensing Operating

Non-operating

5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature

Shock Operating Non-operating 40 G, 2 ms, half-sine 200 G, 2 ms, half-sine

Random Vibration Operating 0.75 grms

Non-operating 1.50 grms

Maximum Altitude (unpressurized)

-50 to 10,000 ft. (-15.24 to 3,048 m) Operating Non-operating -50 to 15,000 ft. (-15.24 to 12,192 m)

Planned Industry Standard Certifications

UL Yes **CSA** Yes **FCC Compliance** Yes

ENERGY STAR® Yes **EPEAT®** Yes **ICES** Yes Australia / NZ A-Tick Yes

Compliance

CCC Yes **Japan VCCI Compliance** Yes **KCC** Yes **BSMI** Yes **CE Marking Compliance** Yes MIL STD 810H Yes **BNCI or BELUS** Yes **GOST** Yes Saudi Arabian

Compliance (ICCP) Yes **UKRSERTCOMPUTER** Yes



¹Configurations of the HP ZBook Fury 15.6 inch G8 that are ENERGY STAR® qualified are identified as HP ZBook Fury 15.6 inch G8 ENERGY STAR on HP websites and on http://www.energystar.gov.

² EPEAT® registered where applicable. EPEAT registration varies by country. See http://www.epeat.net for registration status by country. Search keyword generator on HP's 3rd party option store for solar generator accessories at www.hp.com/go/options.

Technical Specifications – Displays

DISPLAYS

15.6" diagonal FHD IPS
eDP1.2 anti-glare WLEDbacklit and ambient light
sensor 250 nits 45% NTSC
(1920 x 1080)

Outline
Active A
Weight
Diagonal

 Outline Dimensions (W x H)
 350.96 x 216.65 mm (max)

 Active Area
 344.16 x 193.59 mm (typ.)

Weight 370 g (max)

Diagonal Size 15.6 inch

Thickness 3.2 mm (max)

Interface eDP 1.2

Panel Technology IPS

Surface Treatment Anti-Glare

Touch Enabled No

Refresh Rate 60 Hz

Brightness

Pixel Resolution Format 1920 x 1080 (FHD)

250nits

Configuration RGB

BacklightLEDPPI166Color Gamut Coverage45% NTSCColor Depth6 bits + Hi FRCViewing AngleUWVA 85/85/85/85

All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

15.6" diagonal FHD IPS eDP1.3 + PSR anti-glare WLED-backlit and ambient light sensor 400 nits 72% NTSC (1920 x 1080)

 Outline Dimensions (W x H)
 350.96 x 216.75 mm (max)

 Active Area
 344.16 x 193.59 mm (typ.)

Weight 370 g (max)

Diagonal Size 15.6 inch

Thickness 3.2 mm (max)

Interface eDP 1.3 + PSR

Panel TechnologyIPSSurface TreatmentAnti-Glare

Touch EnabledNoRefresh Rate60 HzBrightness400 nits

Pixel Resolution Format 1920 x 1080 (FHD)

Configuration RGB

Backlight LED
PPI 142
Color Gamut Coverage 72% NTSC
Color Depth 6 bits + Hi FRC
Viewing Angle UWVA 85/85/85/85

All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.



Technical Specifications – Displays

Next Gen HP SureView Reflect 15.6" diagonal FHD IPS eDP1.3 + PSR anti-glare WLED-backlit and ambient light sensor 1000 nits 72% NTSC (1920 x 1080)

Outline Dimensions (W x H) 349.52 x 205.39 (mm) max

Active Area 344.16 x 193.59 tvp.

Weight 370g max. Diagonal Size 15.6 inch

Thickness 2.6mm / 4.5mm max. (PCB)

Interface eDP **IPS** Panel Technology

Surface Treatment Anti-Glare

Touch Enabled No

Contrast Ratio 1500:1 (typ.)

Refresh Rate 60Hz **Brightness** 1000 nits

Pitch **Pixel Resolution** 1920 x 1080 (FHD)

> **Format RGB**

LED Backlight PPI 141 **Color Gamut Coverage 72% NTSC** Color Depth 8 bits

Viewing Angle UWVA 85/85/85/85

All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

Next Gen HP Dream Color Outline Dimensions (W x H) display 15.6" diagonal UHD IPS 120Hz eDP1.4 + PSR2 anti-glare BV LEDbacklit and ambient light sensor 600 nits 100% DCI-P3 (3840 x 2160)

350.22 x 216.27 mm (max) **Active Area** 344.22 x 193.62 (mm)

Weight 300g max. Diagonal Size 15.6 inch **Thickness** 2.6 (mm) max eDP 1.4 + PSR2 Interface

IPS Panel Technology **Surface Treatment** Anti-Glare

Touch Enabled No

Contrast Ratio 1200:1 (typ.) Refresh Rate 120Hz 600 nits **Briahtness**

Pixel Resolution Pitch 3840 x 2160 (UHD)

> **Format RGB**

LED Backlight PPI 282

Color Gamut Coverage 100% DCI-P3

Delta E <2 **Color Depth** 8 bits

UWVA 85/85/85/85 Viewing Angle

All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.



backlit touch screen with

Corning® Gorilla® Glass 5

600 nits 100% DCI-P3

Technical Specifications - Displays

15.6" diagonal UHD (3840 Outline Dimensions (W x H) 350.22 x 216.27 mm (max) x 2160) IPS HDR 400 **Active Area** 344.22 x 193.62 (mm) eDP1.4 + PSR2 WLED-

Weight 300g max. 15.6 inch Diagonal Size and ambient light sensor Thickness 2.6 (mm) max eDP 1.4 + PSR2 Interface

> **IPS** Panel Technology

Surface Treatment Anti-Glare

Touch Enabled Yes

Contrast Ratio 1200:1 (typ.) Refresh Rate 120Hz **Brightness** 600 nits

Pixel Resolution Pitch 3840 x 2160 (UHD)

> **Format RGB**

Backlight LED PPI 282

Color Gamut Coverage 100% DCI-P3

Delta E <2 **Color Depth** 8 bits

Viewing Angle UWVA 85/85/85/85

All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.



Technical Specifications – Storage

STORAGE AND DRIVES

256GB PCIe NVMe TLC M.2 Form Factor
2280 Solid State Drive

Form Factor M.2 2280

Drive Weight 0.02 lb (10 g)

Capacity 256GB

NAND Type TLC

Height 2.3 mm Max

 Height
 2.3 mm Max

 Width
 0.87 in (22 mm)

 Interface
 PCIe® Gen3 x4 NVMe™

Performance Maximum Sequential Read Maximum Sequential Write

2580 MB/s \sim 2600 MB/s 1000 MB/s \sim 1100 MB/s

Logical Blocks 500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security, TRIM; L1.2

For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

Slot 1 – 4 supports up to PCIe Gen 3 speeds

256GB PCIe NVMe TLC M.2 Form Factor 2280 SED Opal 2 Solid Drive Weight State Drive

Form Factor M.2 2280

Drive Weight 0.02 lb (10 g)

Capacity 256GB

NAND Type TLC

 Height
 2.3 mm Max

 Width
 0.87 in (22 mm)

 Interface
 PCIe® Gen3 x4 NVMe™

Performance Maximum Sequential Read Maximum Sequential Write

2580 MB/s \sim 2600 MB/s 1000 MB/s \sim 1100 MB/s

Logical Blocks 500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security (Option); TCG Opal 2.0; TRIM; L1.2

For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

Slot 1 – 4 supports up to PCIe Gen 3 speeds

512GB PCIe NVMe TLC M.2 Form Factor 2280 Solid State Drive Drive Weight

Form Factor M.2 2280

Drive Weight 0.02 lb (10 g)

Capacity 512GB

NAND Type TLC

 Height
 2.3 mm Max

 Width
 0.87 in (22 mm)

 Interface
 PCIe® Gen3 x4 NVMe™

Performance Maximum Sequential Read Maximum Sequential Write

3400 MB/s 2956 MB/s

Logical Blocks 1,000,215,216

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security, TRIM; L1.2



Technical Specifications – Storage

For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

Slot 1 – 4 supports up to PCIe Gen 3 speeds

512TB PCIe NVMe TLC M.2 Form Factor 2280 SED Opal 2 Solid

State Drive

M.2 2280 **Drive Weight** 0.02 lb (10 g) Capacity 512GB **NAND Type** TLC

Height 2.3 mm Max Width 0.87 in (22 mm) Interface PCIe® Gen3 x4 NVMe™

Performance **Maximum Sequential Read Maximum Sequential Write**

> 3400 MB/s 2500 MB/s

Logical Blocks 1.000,215,216

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp] **Features** ATA Security (Option); TCG Opal 2.0; TRIM; L1.2

> For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

Slot 1 – 4 supports up to PCIe Gen 3 speeds

1TB PCIe NVMe TLC M.2 2280 Solid State Drive

Form Factor M.2 2280 **Drive Weight** 0.02 lb (10 q)

Capacity 1TB **NAND Type** TLC

Height 2.3 mm Max Width 0.87 in (22 mm) Interface PCIe® Gen3 x4 NVMe™

Performance Maximum Sequential Read Maximum Sequential Write

> 3480 MB/s 2800 MB/s

Logical Blocks 2.000.409.264

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security, TRIM; L1.2

Available in RAID 1 config Yes

For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

Slot 1 – 4 supports up to PCIe Gen 3 speeds

2TB PCIe NVMe TLC M.2 2280 Solid State Drive

Form Factor M.2 2280 **Drive Weight** 0.02 lb (10 q)

Capacity 2TB TLC **NAND Type**

Height 2.3 mm Max Width 0.87 in (22 mm) Interface PCIe® Gen3 x4 NVMe™

Performance Maximum Sequential Read **Maximum Sequential Write**

> 3180 MB/s 2920 MB/s

Technical Specifications – Storage

Logical Blocks 3,907,029,168

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security, TRIM; L1.2

Available in RAID 1 config Yes

For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

Slot 1 – 4 supports up to PCIe Gen 3 speeds

500GB SATA 2.5" HDD Form Factor 2.5"

Drive Weight 0.21 lbs (95 g)

Capacity 500GB

 Height
 0.28 in (7 mm)

 Width
 2.75 in (69.85 mm)

 Interface
 ATA-8, SATA 3.0

Performance Maximum Sequential Read Maximum Sequential Write

120MB/s 120MB/s

Logical Blocks 976,773,168

Operating Temperature 32° to 140° F (0° to 60° C) [case temp]

Features ATA Security; S.M.A.R.T., NCQ, Ultra DMA, DIPM, HIPM

Notes: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

500GB SATA 2.5" SED HDD Form Factor 2.5"

- FIPS-140-2

Drive Weight 0.21 lbs (95 g)

Capacity 500GB

 Height
 0.28 in (7 mm)

 Width
 2.75 in (69.85 mm)

 Interface
 ATA-8, SATA 3.0

Performance Maximum Sequential Read Maximum Sequential Write

120MB/s 120MB/s

Logical Blocks 976,773,168

Operating Temperature 32° to 140° F (0° to 60° C) [case temp]

Features ATA Security; S.M.A.R.T., NCQ, Ultra DMA, DIPM, HIPM

Notes: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

1TB SATA 2.5" HDD Form Factor 2.5"

Drive Weight 0.21 lbs (95 g)

Capacity 1TB

 Height
 0.28 in (7 mm)

 Width
 2.75 in (69.85 mm)

 Interface
 ATA-8, SATA 3.0

Performance Maximum Sequential Read Maximum Sequential Write

120MB/s 120MB/s

Logical Blocks 1,953,525,168

Technical Specifications – Storage

Operating Temperature 32° to 140° F (0° to 60° C) [case temp]

Features ATA Security; S.M.A.R.T., NCQ, Ultra DMA, DIPM, HIPM

Notes: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

2TB SATA 2.5" HDD Form Factor 2.5"

Drive Weight 0.21 lbs (95 g)

Capacity 2TB

 Height
 0.28 in (7 mm)

 Width
 2.75 in (69.85 mm)

 Interface
 ATA-8, SATA 3.0

Performance Maximum Sequential Read Maximum Sequential Write

100MB/s 100MB/s

Logical Blocks 3,907,029,168

Operating Temperature 32° to 140° F (0° to 60° C) [case temp]

Features ATA Security; S.M.A.R.T., NCQ, Ultra DMA, DIPM, HIPM

Notes: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

1TB PCIe NVMe TLC M.2 2280 SED Opal 2 Solid

State Drive

Form Factor M.2 2280

Drive Weight 0.02 lb (10 g)

Capacity 1TB NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Interface
 PCIe® Gen3 x4 NVMe™

Performance Maximum Sequential Read Maximum Sequential Write

Up to 3500 MB/s Up to 3000 MB/s

Logical Blocks 2,000,409,264

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security (Option); TCG Opal 2.0; TRIM; L1.2;

Notes: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

2TB PCIe NVMe TLC M.2 2280 SED Opal 2 Solid

State Drive

Form Factor M.2 2280

Drive Weight 0.02 lb (10 q)

Capacity 2TB NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Interface
 PCIe® Gen3 x4 NVMe™

Performance Maximum Sequential Read Maximum Sequential Write

Technical Specifications – Storage

Logical Blocks 4,000,797,360

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security (Option); TCG Opal 2.0; TRIM; L1.2;

Notes: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

SSD 256GB 2280 PCIe-4x4 Form Factor NVMe Three Layer Cell Capacity

Form Factor M.2 2280
Capacity 256 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (<10 g)</td>

Interface PCIe® Gen4 x4 NVMe™

Performance Maximum Sequential Read Maximum Sequential Write

Up to 6,400 MB/s Up to 2,700 MB/s

Logical Blocks 500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features Pyrite 2.0; TRIM; L1.2;

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

SSD 512GB 2280 PCIe-4x4 Form Factor
NVMe Three Layer Cell Canacity

Form Factor M.2 2280
Capacity 512 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (<10 g)</td>

Interface PCIe® Gen4 x4 NVMe™

Performance Maximum Sequential Read Maximum Sequential Write

Up to 6,600 MB/s Up to 5,100 MB/s

Logical Blocks 1,000,215,216

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features Pyrite 2.0; TRIM; L1.2;

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

SSD 1TB 2280 PCIe-4x4 NVMe Three Layer Cell Form Factor M.2 2280
Capacity 1TB
NAND Type TLC

Height 0.09 in (2.3 mm)

Technical Specifications – Storage

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (<10 g)</td>

Interface PCIe[®] Gen4 x4 NVMe[™]

Performance Maximum Sequential Read Maximum Sequential Write

Up to 7,100 MB/s Up to 5,200 MB/s

Logical Blocks 2,000,409,264

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features Pyrite 2.0; TRIM; L1.2;

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

SSD 2TB 2280 PCIe-4x4 NVMe Three Layer Cell Form Factor M.2 2280
Capacity 2TB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (<10 g)</td>

Interface PCIe® Gen4 x4 NVMe™

Performance Maximum Sequential Read Maximum Sequential Write

Up to 7,100 MB/s Up to 5,200 MB/s

Logical Blocks 4,000,797,360

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features Pyrite 2.0; TRIM; L1.2;

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

256GB PCIe-4x4 2280 NVME Self Encrypted OPAL2 Three Layer Cell Solid State Drive Form Factor M.2 2280
Capacity 256 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (<10 g)</td>

Interface PCIe® Gen4 x4 NVMe™

Performance Maximum Sequential Read Maximum Sequential Write

6.400 MB/s 2.700 MB/s

Logical Blocks 500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security (Option); TCG Opal 2.0; TRIM; L1.2;

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.



Technical Specifications - Storage

512GB PCIe-4x4 2280 NVME Self Encrypted OPAL2 Three Layer Cell Solid State Drive Form Factor M.2 2280
Capacity 512 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (<10 g)</td>

Interface PCIe[®] Gen4 x4 NVMe[™]

Performance Maximum Sequential Read Maximum Sequential Write

6,600 MB/s 5,100 MB/s

Logical Blocks 1,000,215,216

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security (Option); TCG Opal 2.0; TRIM; L1.2;

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

Technical Specifications – Networking

NETWORKING/COMMUNICATION

Intel i219LM 10/100/1000 Connector

Integrated NIC vPro™

RJ-45 System Interface PCI(Intel proprietary) + SMBus

Data rates supported 10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14)

> 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40)

Auto-Negotiation (Automatic Speed Selection)

Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100

Mbit/s

IEEE Compliance IEEE 802.1p QoS (Quality of Service) Support

IEEE 802.1q VLAN support

IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)

IEEE 802.3az EEE (Energy Efficient Ethernet)

Performance TCP/IP/UDP Checksum Offload (configurable)

Protocol Offload (ARP & NS)

Large send offload and Giant send offload Receiving Side Scaling(Hash Mode Only)

Jumbo Frame 9K

Cable Disconnection: 25mW Power consumption

100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(\$3/\$4/\$5): 50mW WoL Disable(S3/S4/S5): 25mW

ACPI compliant - multiple power modes Power

Management Situation-sensitive features reduce power consumption

Advanced link down power saving for reducing link down power

consumption

Management Interface

Auto MDI/MDIX Crossover cable detection

IT Manageability

Wake-on-LAN from modem standby or sleep state (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only)

PXE 2.1 Remote Boot

Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x,

clause 30))

Comprehensive diagnostic and configuration software suite

Virtual Cable Doctor for Ethernet cable status

Intel® vPro™ support with appropriate Intel® chipset components Security & Manageability

Intel i219v 10/100/1000 Integrated NIC non-vPro™

Connector **RJ-45**

System Interface PCI(Intel proprietary) + SMBus

10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) **Data rates supported**

> 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40)

Auto-Negotiation (Automatic Speed Selection)

Full Duplex Operation at all Speeds, Half Duplex operation at 10, 100 &

1000 Mbit/s

IEEE Compliance IEEE 802.1p QoS (Quality of Service) Support

IEEE 802.1q VLAN support



Technical Specifications – Networking

IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)

IEEE 802.3az EEE (Energy Efficient Ethernet)

IEEE 802.3i 10BASE-T IEEE 802.3u 100BASE-TX IEEE 802.3ab 1000BAE-T IEEE 802.3bz 2.5GBASE-T

Performance TCP/IP/UDP Checksum Offload (configurable)

Protocol Offload (ARP & NS)

Large send offload and Giant send offload Receiving Side Scaling(Hash Mode only)

Jumbo Frame 9K

Power consumption Cable Disconnection: 25mW

> 100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(\$3/\$4/\$5): 50mW WoL Disable(S3/S4/S5): 25mW

Power ACPI compliant - multiple power modes

Situation-sensitive features reduce power consumption Management

Advanced link down power saving for reducing link down power

consumption

Management Interface

Auto MDI/MDIX Crossover cable detection IT Manageability Wake-on-LAN from modem standby or sleep state (Magic Packet and

Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only)

PXE 2.1 Remote Boot

Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x,

clause 30))

Comprehensive diagnostic and configuration software suite

Virtual Cable Doctor for Ethernet cable status

NFC (Near Field Communication) module (optional)

Dimensions (L x W x H) Module 50 mm by 23 mm by 2.89 mm

Chipset SiM3U156+SiM3U154+AMS3911

System interface **USB 2.0**

System interface (I/O) Audio signal output on card read

NFC RF standards ISO/IEC 14443 A (In reading CSN) ISO/IEC 14443 B ISO/IEC 15693

ISO/IEC 18092 ECMA-340 NFCIP-1

NFC Forum Support Tag Type 1, Type 2, Type3 and Type 4 in reading CSN

Reader Mode 13.56MHz:

> ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 MIFARE 1K MIFARE 4K MIFARE DESFire

FeliCa Topaz cards HID iClass ISO



Technical Specifications – Networking

125kHz: **HID Prox UID AWID UID CASI-RUSCO UID EM 410x UID** Indana ASP/ASP+ UID

13.56MHz and 125kHz

NFC Modes Supported Reader

Raw RF Data Rates 106, 212 kbps

Operating

Frequency

temperature -30°C to 70°C -40°C to 80°C Storage temperature Humidity 10-90% operating 5-95% non-operating

Supply Operating

voltage 4.35 to 5.25 Volts

Power Consumption Mode Power Consumption, Typical

> **Polling** 75mA Communication 85mA

Antenna 13.56MHz/125kHz combo antenna. Antenna connector, 0.5mm pitch, 16pin

connector FPC.

Intel Wi-Fi 6 AX201 + BT5.2 (802.11ax 2x2, non-vPro, supporting gigabit data rate*)** non-vPro

Wireless LAN Standards

IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v

IEEE 802.11a

Interoperability Wi-Fi certified **Frequency Band** 802.11b/g/n/ax

> • 2.402 - 2.482 GHz 802.11a/n/ac/ax • 4.9 - 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 - 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz

Data Rates • 802.11b: 1, 2, 5.5, 11 Mbps

> • 802.11q: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz &

160MHz)

802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz

& 160MHz)



Technical Specifications – Networking

Output Power²

Modulation Direct Sequence Spread Spectrum

OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

, 1024QAM

• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/q

mode only

• AES-CCMP: 128 bit in hardware

802.1x authentication

• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

WPA2 and WPA3 certification

• IEEE 802.11i

WAPI

Network Architecture Ad-hoc (Peer to Peer)

Models Infrastructure (Access Point Required)

Roaming IEEE 802.11 compliant roaming between access points

802.11b: +18.5dBm minimum
802.11g: +17.5dBm minimum
802.11a: +18.5dBm minimum

802.11n HT20(2.4GHz): +15.5dBm minimum
802.11n HT40(2.4GHz): +14.5dBm minimum
802.11n HT20(5GHz): +15.5dBm minimum
802.11n HT40(5GHz): +14.5dBm minimum
802.11ac VHT80(5GHz): +11.5dBm minimum
802.11ac VHT160(5GHz): +11.5dBm minimum

802.11ax HT40(2.4GHz): +10dBm minimum
 802.11ax VHT160(5GHz): +10dBm minimum

Power Consumption • Transmit mode 2.0 W

• Receive mode 1.6 W

Idle mode (PSP) 180 mW (WLAN Associated)
Idle mode 50 mW (WLAN unassociated)

• Connected Standby 10mW

· Radio disabled 8 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity³ •802.11b, 1Mbps : -93.5dBm maximum

•802.11b, 11Mbps: -84dBm maximum
•802.11a/g, 6Mbps: -86dBm maximum
•802.11a/g, 54Mbps: -72dBm maximum
•802.11n, MCS07: -67dBm maximum
•802.11n, MCS15: -64dBm maximum
•802.11ac, MCS0: -84dBm maximum

802.11ac, MCS0: -84dBm maximum
 802.11ac, MCS9: -59dBm maximum
 802.11ax, MCS11(HT40): -59dBm maximum

•802.11ax, MCS11(H140). -59uBill Haxillulli •802.11ax, MCS11(VHT160): -58.5dBm maximum

Antenna Type High efficiency antenna with spatial diversity, mounted in the

display enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth

communications

Form Factor PCI-Express M.2 MiniCard with CNVi Interface

Dimensions 1. Type 2230 : 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm

Technical Specifications – Networking

Weight 1. Type 2230 : 2.8g

2. Type 126: 1.3g

Operating Voltage 3.3v +/- 9%

Temperature Operating 14° to 158° F (-10° to 70° C)

Non-operating -40° to 176° F (-40° to 80° C)

Humidity Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)

Altitude Operating Non- 0 to 10,000 ft (3,048 m)

operating 0 to 50,000 ft (15,240 m)

LED Activity

LED Amber — Radio Off; LED Off — Radio ON

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1/5.2 Wireless Technology

Frequency Band 2402 to 2480 MHz

Number of Available Channels Legacy : 0~79 (1 MHz/CH)

BLE: 0~39 (2 MHz/CH)

Data Rates and Throughput Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps

BLE: 1 Mbps data rate; throughput up to 0.2 Mbps

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps,

voice channels

Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth

device with a maximum transmit power of + 9.5 dBm for BR and

EDR.

Power Consumption Peak (Tx): 330 mW

Peak (Rx): 230 mW Selective Suspend: 17 mW

Bluetooth Software Supported

Link Topology

Microsoft Windows Bluetooth Software

Power Management Microsoft Windows ACPI, and USB Bus Support

Certifications FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power Management ETS 300 328, ETS 300 826
Certifications Low Voltage Directive IEC950

UL, CSA, and CE Mark

Bluetooth Profiles Supported BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping LE Dual Mode LE Link Layer

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan

BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)



Technical Specifications – Networking

*GbE - The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

**Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax WLAN devices. Only available in countries where 802.11ax is supported.

Intel Wi-Fi 6 AX201 + BT5.2 (802.11ax 2x2, vPro, supporting gigabit data rate*)** vPro Wireless LAN Standards

IEEE 802.11a
IEEE 802.11g
IEEE 802.11n
IEEE 802.11ac
IEEE 802.11ax
IEEE 802.11d
IEEE 802.11d
IEEE 802.11h
IEEE 802.11h
IEEE 802.11i
IEEE 802.11k

IEEE 802.11v
Interoperability Wi-Fi certified
Frequency Band 802.11b/g/n/ax

2.402 – 2.482 GHz
802.11a/n/ac/ax
4.9 – 4.95 GHz (Japan)
5.15 – 5.25 GHz
5.25 – 5.35 GHz
5.47 – 5.725 GHz
5.825 – 5.850 GHz

IEEE 802.11r

Data Rates

• 802.11b: 1, 2, 5.5, 11 Mbps

802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz &

160MHz)

802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz

& 160MHz)

Modulation Direct Sequence Spread Spectrum

OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

, 1024QAM

Security¹ • IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/q

mode only

• AES-CCMP: 128 bit in hardware

• 802.1x authentication

• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

WPA2 and WPA3 certification

• IEEE 802.11i

WAPI



Technical Specifications – Networking

Ad-hoc (Peer to Peer) **Network Architecture**

Models Infrastructure (Access Point Required)

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Output Power² • 802.11b: +18.5dBm minimum

• 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum

• 802.11n HT20(2.4GHz): +15.5dBm minimum • 802.11n HT40(2.4GHz): +14.5dBm minimum 802.11n HT20(5GHz): +15.5dBm minimum 802.11n HT40(5GHz): +14.5dBm minimum 802.11ac VHT80(5GHz): +11.5dBm minimum • 802.11ac VHT160(5GHz): +11.5dBm minimum

• 802.11ax HT40(2.4GHz): +10dBm minimum

802.11ax VHT160(5GHz): +10dBm minimum

Power Consumption • Transmit mode: 2.0 W

Receive mode: 1.6 W

• Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode:50 mW (WLAN unassociated) Connected Standby/Modern Standby: 10mW

Radio disabled: 8 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity³ •802.11b, 1Mbps: -93.5dBm maximum

•802.11b, 11Mbps: -84dBm maximum • 802.11a/g, 6Mbps: -86dBm maximum • 802.11a/q, 54Mbps: -72dBm maximum • 802.11n, MCS07: -67dBm maximum • 802.11n, MCS15: -64dBm maximum • 802.11ac, MCS0: -84dBm maximum • 802.11ac, MCS9: -59dBm maximum •802.11ax, MCS11(HT40): -59dBm maximum

•802.11ax, MCS11(VHT160): -58.5dBm maximum High efficiency antenna with spatial diversity, mounted in the

display enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the

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Dimensions 1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm

Weight 1. Type 2230: 2.8g

2. Type 126: 1.3q

Operating Voltage 3.3v +/- 9%

Antenna Type

Operating 14° to 158° F (-10° to 70° C) **Temperature**

-40° to 176° F (-40° to 80° C) Non-operating

Humidity Operating 10% to 90% (non-condensing) Non-operating 5% to 95% (non-condensing)

Operating Non-0 to 10,000 ft (3,048 m)

Altitude operating 0 to 50,000 ft (15,240 m)

LED Activity LED Amber - Radio OFF; LED White - Radio ON

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1/5.2 Wireless Technology



Technical Specifications - Networking

Frequency Band 2402 to 2480 MHz

Number of Available Channels Legacy : 0~79 (1 MHz/CH)

BLE: 0~39 (2 MHz/CH)

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Legacy: Synchronous Connection Oriented links up to 3, 64 kbps,

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Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth

device with a maximum transmit power of + 9.5 dBm for BR and

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Power Consumption Peak (Tx): 330 mW

Peak (Rx): 230 mW Selective Suspend: 17 mW

Bluetooth Software Supported

Link Topology

Power Management

Microsoft Windows Bluetooth Software

Microsoft Windows ACPI, and USB Bus Support

Certifications FCC (47 CFR) Part 15C, Section 15.247 & 15.249 **Power Management** ETS 300 328, ETS 300 826

Certifications Low Voltage Directive IEC950

UL, CSA, and CE Mark

Bluetooth Profiles Supported BT4.1-ESR 5/6/7 Compliance

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LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

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LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy

LE Privacy 1.2 -Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

Security & Manageability Intel® vPro™ support with appropriate Intel® chipset components

*GbE - The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

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Technical Specifications – Networking

Intel® XMM™ 7360 LTE-Advanced CAT9 (Pandora)*

Technology/Operating

FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3),

bands

1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 1400 (Band 11), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 17 lower), 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1400 (Band 21), 850 (Band 26), 700 (Band 28), 700 (Band 29 RX only), 2300 (Band 30), 1700/2100

(Band 66).

TDD LTE: 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band 41).

HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4),

850 (Band 5), 900 (Band 8) MHz

throughput up to 50Mbps

Wireless protocol

3GPP Release 11 LTE Specification CAT.9, DL 60MHz BW throughput up to 450Mbps; UL 20MHz

standards

WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification

GPS Standalone, A-GPS (MS-A, MS-B)

GPS bands 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098 MHz

Maximum data rates LTE: 450 Mbps (Download), 50 Mbps (Upload)

DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21 Mbps (Download), 5.76 Mbps (Upload)

Maximum output power

LTE: 23 dBm HSPA+: 23.5 dBm

Maximum power consumption

LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)

Form Factor M.2, 3042-S3 Key B

Weight 5.8 g

Dimensions 42 x 30 x 2.3 mm

(Length x Width x Thickness)

* Mobile Broadband is an optional feature and requires configuration at purchase. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

Near Field Communications Controller (optional)

Dimensions (L x W x H) Module 25 mm by 10 mm by 2.0 mm

Chipset NPC100 System interface I2C

NFC RF standards ISO/IEC 14443 A

ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092

ECMA-340 NFCIP-1 Target and Initiator

ECMA-320 NFCIP-2

NFC Forum Support Tag Type 1, Type 2, Type3 and Type 4, NFCIP-1 and NFCIP-2

Reader (PCD-VCD) Mode(1) ISO/IEC 14443 A ISO/IEC 14443 B

ISO/IEC 15693 MIFARE 1K MIFARE 4K



Technical Specifications - Networking

MIFARE DESFire

FeliCa

Jewel and Topaz cards

Card Emulation (PICC- ISO/IEC 14443 A VICC) Mode(1)

ISO/IEC 14443 B and B'

MIFARE

FeliCa

Frequency 13.56 MHz

NFC Modes Supported Reader/Writer, Peer-to-Peer **Raw RF Data Rates** 106, 212, 424, 848 kbps

Operating

temperature 0°C to 70°C Storage temperature -20°C to 125°C Humidity 10-90% operating 5-95% non-operating

Supply Operating

voltage 4.35 to 5.25 Volts I/O Voltage 1.8V or 3.3V

Power Consumption Booster enable, **VBAT= 3.3V,**

> $VCC_BOOST = 5V$ Polling Mode Power

Consumption, **Typical**

7.3 mA **Detected Test** Total 283.8 mA Tag Type 1 Net Module 236.8 mA

Detected Test Total 288.8 mA Tag Type 2 Net Module 241.8 mA **Detected Test** Total 287.7 mA

Tag Type 3 Net Module 240.7 mA **Detected Test** Total 282.3 mA Net Module 235.3 mA Tag Type 4

Antenna Antenna connector, 0.5mm pitch, 7 connector FPC. Antenna matching is

external to module.



Technical Specifications – Power

POWER

120 Watt Slim Smart AC Adapter

 Dimensions
 138x68.5x25.4mm

 Weight
 unit: 350g +/- 10g

Input Input Efficiency 88% at 115 Vac and 89% at 230 Vac

Input frequency range 47 ~ 63 Hz

Input AC current 1.7 A at 90 Vac and Maximum Load

Output Output power 120W

DC output 19.5V

Hold-up time 5ms at 115 Vac input

Output current limit <18.0A

Connector C5

Environmental DesignOperating
32° to 95° F (0° to 35° C)

temperature

Non-operating (storage) temperature -4° to 185° F (-20° to 85° C)

Altitude 0 to 16,400 ft (0 to 5,000 m)

Humidity 5% to 95% Storage Humidity 5% to 95%

EMI and Safety Certifications Eg

*CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

* MTBF - over 200,000 hours at 25°C ambient condition.

150 Watt Slim Smart AC Adapter

Dimensions138x66x22mmWeightunit: 325g +/- 10g

Input Input Efficiency 88% at 115 Vac and 89% at 230Vac

Input frequency range 47 ~ 63 Hz

Input AC current 2.7 A at 90 Vac and Maximum Load

Output Output power 150W

DC output 19.5V

Hold-up time 5ms at 115 Vac input

Output current limit <16.0A

Connector C5

Environmental Design Operating 32° to 95° F (0° to 35° C)

temperature

Non-operating -4° to 185° F (-20° to 85° C)

(storage) temperature

Altitude 0 to 16,400 ft (0 to 5000m)



^{*}Can only be configured with Intel UMA Graphics option

Technical Specifications – Power

Humidity 5% to 95% Storage Humidity 5% to 95%

EMI and Safety Certifications

*CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. * MTBF - over 200,000 hours at 25°C ambient condition.

*Can only be configured with NVIDIA T1200 and A2000 Graphics option

200 Watt UltraSlim Smart Dimensions **AC Adapter**

152x73x23.5mm Weiaht unit: 530g +/- 10g

Input **Input Efficiency** 88% at 115 Vac and 89% at 230Vac

> Input frequency range 47 ~ 63 Hz

Input AC current 2.9 A at 90 Vac and Maximum Load

Output **Output power** 200W

DC output 19.5V

Hold-up time 5ms at 115 Vac input

Output current limit <16.0A

Connector C13

Environmental Design Operating 32° to 95° F (0° to 35° C)

temperature

Non-operating (storage)

temperature

-4° to 185° F (-20° to 85° C)

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity 5% to 95% **Storage Humidity** 5% to 95%

EMI and Safety

Certifications *CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC

Class B. CISPR22 Class B. CCC. NOM-1 NYCE.

* MTBF - over 100,000 hours at 25°C ambient condition.

*Can only be configured with RTX A3000, RTX A4000, RTX A5000 Graphics and Radeon W6600M **Graphics option**



Technical Specifications – Power

HP Long Life 8-cell Polymer (94Wh) Battery Weight 414.5g Cells/Type 8 cell

Energy Voltage 11.55V

Amp-hour capacity 4.15Ah

Operating (Charging) 0° to 60° C

Operating (Discharging) -20° to 70° C

Fuel Gauge LED NA

Warranty Depends on system offering

Optional Travel Battery No

Available

Temperature

*Actual battery Watt-hours (Wh) will vary from design capacity. Battery capacity will naturally decrease with shelf life, time, usage, environment, temperature, system configuration, loaded apps, features, power management settings and other factors.

Refer to http://www.hp.com/support/batterywarranty/ for battery warranty information.

Note: batteries are customer replaceable.



Technical Specifications – Environmental

ENVIRONMENTAL DATA

Eco-Label Certifications & declarations

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- **US ENERGY STAR®**
- US Federal Energy Management Program (FEMP)
- EPEAT[®] Gold registered in the United States. See http://www.epeat.net for registration status in your country.
- TCO certified
- China Energy Conservation Program (CECP)
- China State Environmental Protection Administration (SEPA)
- Taiwan Green Mark
- Korea Eco-label
- Japan PC Green label*

Sustainable Impact **Specifications**

- 10% post-consumer recycled plastic
- External Power Supply 90% Efficiency
- Low halogen
- Outside Box and corrugated cushions are 100% sustainably sourced and recyclable
- Molded Paper Pulp Cushion inside box is 100% sustainably sourced and recyclable
- Bulk packaging available

System Configuration

The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a "Typically Configured Notebook".

Energy Consumption (in accordance with US ENERGY STAR® test method)

STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	13.73 W	13.82 W	13.88 W
Normal Operation (Long idle)	1.68 W	1.80 W	1.76 W
Sleep	1.68 W	1.80 W	1.76 W
Off	0.43 W	0.44 W	0.42 W

NOTE:

Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	47 BTU/hr	47 BTU/hr	47 BTU/hr
Normal Operation (Long idle)	6 BTU/hr	6 BTU/hr	6 BTU/hr
Sleep	6 BTU/hr	6 BTU/hr	6 BTU/hr
Off	1 BTU/hr	1 BTU/hr	1 BTU/hr

*NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.



Technical Specifications – Environmental

Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L _{WAd} , bels)	Sound Pressure (L _{pAm} , decibels)
Typically Configured – Idle	2.6	13.8
Fixed Disk – Random writes	2.7	15.8
Optical Drive – Sequential reads	2.9	19.5

Longevity and Upgrading

This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the

Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive 2011/65/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level, see www.epeat.net
- Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.
- This product is 94% recycle-able when properly disposed of at end of life.

Packaging Materials	External:	PAPER/Corrugated	306 g
	Internal:	PAPER/Molded pulp	181 g
		PLASTIC/Polyethylene low density	13 g
		PLASTIC/polypropylene	5 g

The plastic packaging material contains at least 57% recycled content.

The corrugated paper packaging materials contains at least 59% recycled content.

RoHS Compliance

HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam.

We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products.

We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve.

To obtain a copy of the HP RoHS Compliance Statement, see HP RoHS position statement.

Material Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at

http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html



Technical Specifications – Environmental

):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Bis(2-Ethylhexyl) phthalate (DEHP)
- Benzyl butyl phthalate (BBP)
- Dibutyl phthalate (DBP)
- Diisobutyl phthalate (DIBP)
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging Usage

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.



Technical Specifications – Environmental

HP Inc. Corporate Environmental For more information about HP's commitment to the environment: **Information**

Global Citizenship Report

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

Eco-label certifications

http://www8.hp.com/us/en/hp-information/environment/ecolabels.html

ISO 14001 certificates:

http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842

and

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

footnotes

- Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard.
- External power supplies, WWAN modules, power cords, cables and peripherals excluded.
- 100% outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers.
- Fiber cushions made from 100% recycled wood fiber and organic materials.

Options and Accessories (sold separately and availability may vary by country)

Tuno	Description	Part #
Type Displays	HP Z32 31.5" 4k UHD Display	1AA81A8#XXX
Displays	HP Z38c 37.5" Curved Display	Z4W65A8#XXX
	nr 2300 37.3 Curveu Display	24W03A0#AAA
Case	HP Essential Top Load Case (up to 15.6")	H2W17AA
	HP Essential Backpack (up to 15.6")	H1D24AA
	HP Executive 17.3 Backpack	6KD05AA
	HP Executive 17.3 Top Load	6KD08AA
	HP Business Case(up to 15.6")	2SC66AA
	HP Executive 15.6 Midnight Top Load	1KM15AA
	HP Exec 15.6 Midnight Backpack	1KM16AA
	HP Executive 15.6 Black Leather Top Load	1LG83AA
	HP 17.3 Business Backpack	2SC67AA
	HP 17.3 Business Slim Top Load	2UW02AA
	HP Prelude Pro Recycle Backpack	1X644AA
	HP Prelude Pro Recycle Top Load	1X645AA
	HP Executive 15.6 Top Load	6KD06AA
	HP Executive 15.6 Backpack	6KD07AA
	HP Executive 15.6 Leather Top Load	6KD09AA
	HP Prelude 15.6 Top Load	1E7D7AA
	HP Renew Business 17.3 Laptop Backpack	3E2U5AA
	HP Renew Business 17.3 Laptop Bag	3E2U6AA
	HP Renew Business 15.6 Laptop Bag	3E5F8AA
Docking	HP TB Audio Module (comp with Hook dock)	3AQ21AA
Accessories	HP TB Dock G2 Combo Cable (this is 230W) comp with Hook dock	3XB96AA
Docking station	HP TB Dock G2 w/ Combo Cable (this is 230W)	3TR87AA
_	HP Thunderbolt Dock 230W G2	2UK38AA
	HP USB-C/A Universal Dock G2 Power Not Supported on Mobile Workstations ¹	5TW13AA
	HP USB-C Dock G5 Power Not Supported on Mobile Workstation ¹	5TW10AA
	HP TB Dock 120W G2 w/ Audio ¹	3YE87AA
	¹Up to 100 W via USB-C® (up to 75 W on non HP machines) Separate AC power needed for H	HP ZBooks that
	require more than 100 W power delivered via USB-C® alt mode.	
Input/Output -	HP Comfort Grip Wireless Mouse (See Link 5 Tab)	H2L63AA
Mice	HP 3-button USB Laser Mouse	H4B81AA
	HP Bluetooth Travel Mouse	6SP30AA
	HP USB Travel Mouse	G1K28AA
	HP Wireless Premium Mouse (See Link 5 Tab)	1JR31AA
	HP Elite Presenter Mouse	2CE30AA
	HP Comfort Grip Wireless Mouse (See Link 5 Tab)	H2L63AA
	HP X4000b Bluetooth Mouse	H3T50AA
	HP Wired 320M Mouse	9VA80AA



Options and Accessories (sold separately and availability may vary by country)

	HP 435 Multi-Device Wireless Mouse	3B4Q5AA
Input/Output -	HP Wired Desktop 320MK Mouse and Keyboard	9SR36AA
Keyboard	HP Slim Wireless Keyboard and Mouse	T6L04AA
	HP 320K Wired Keyboard	9SR37AA
	HP Wireless Rechargeable 950MK Mouse and Keyboard	3M165AA
Input/Output -	HP USB-C to USB-A Hub	Z6A00AA
Adapter	HDMI to VGA Adapter	H4F02AA
	HP HDMI to DVI Adapter	F5A28AA
	HP USB-C to USB 3.0 Adapter	N2Z63AA
	HP USB-C to DisplayPort Adapter	N9K78AA
	HP USB-C to VGA Adapter	N9K76AA
	HP Single miniDP-to-DP Adapter Cable	2MY05AA
	HP Elite USB-C Hub	4WX89AA
	HP USB-C to HDMI 2.0 Adapter	1WC36AA
Collaboration	HP BT UC Wireless Duo Headset	W3K09AA
Memory	HP 8GB DDR4 3200 1.2v SODIMM Memory	286H8AA
	HP 16GB DDR4 3200 1.2v SODIMM Memory	286J1AA
	HP 32GB DDR4 2666 SODIMM Memory	6NX83AA
	HP 8GB DDR4 2666 SODIMM ECC Memory	4UY11AA
	HP 16GB DDR4 2666 SODIMM ECC Memory	4UY12AA
Power - A/C	HP 150W 4.5 mm Smart AC Power Adapter	4SC18AA
Adapter	HP 200W 4.5 mm AC Power Adapter	4SC19AA
	HP ZBook 200W Slim Smart 4.5mm AC Adapter	491C7AA
Power - Battery	HP ZBook 94Whr AL Battery	49J06AA
Security	HP Sure Key Cable Lock	6UW42AA
	HP Nano Keyed Cable Lock	1AJ39AA
	HP Nano Dual Head Keyed Cable Lock	1AJ41AA
Storage - External	HP USB DVD-Writer ODD	Y3T76AA
Storage – HDD	HP 500GB 7200 RPM HDD 2.5"	4A1H1AA
2.5"	HP 1TB 7200 RPM HDD 2.5"	4A1H2AA
	HP 2TB 5400 RPM HDD 2.5"	4A1H3AA
Storage - SS M2	HP 1TB 2280 PCIe-3x4 NVME TLC M.2 SSD	6SK99AA
	HP 2GB 2280 PCIe-3x4 NVME TLC M.2 SSD	6SL00AA
	HP 256GB PCIe-3x4 NVME M.2 SSD	1DOH6AA



HP ZBook Fury 15.6 Inch G8 Mobile Workstation PC

Options and Accessories (sold separately and availability may vary by country)

HP 512GB PCI-e 3x4 NVMe M2 SSD 1D0H7AA

HP ZBook Fury G7/G8 HDD & SSD Brackets 48Z98AA

WWAN HP XMM 7360 LTE-Advance WWAN 3FB01AA



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Date of change:	Version History:		Description of change:
August 11, 2021	From v1 to v2	Changed	DISPLAY and WEIGHTS & DIMENSIONS sections
August 17, 2021	From v2 to v3	Changed	POWER section
August 18, 2021	From v3 to v4	Changed	Product Name
August 25, 2021	From v4 to v5	Changed	POWER and Options and Accessories sections
September 10, 2021	From v5 to v6	Changed	POWER section
September 17, 2021	From v6 to v7	Changed	PORTS/SLOTS and STORAGE AND DRIVES sections
September 21, 2021	From v7 to v8	Changed	Options and Accessories section
September 27, 2021	From v8 to v9	Changed	Technical Specifications – Power section
October 4, 2021	From v9 to v10	Changed	MEMORY section
October 6, 2021	From v10 to v11	Changed	MEMORY section
October 22, 2021	From v11 to v12	Changed	MEMORY section
November 11, 2021	From v12 to v13	Changed	OPERATING SYSTEM section

